

Company Profile

2.1 An Introduction to TSMC

Established in 1987 and headquartered in Hsinchu Science Park, Taiwan, TSMC pioneered the pure-play foundry business model by focusing solely on manufacturing customers' designs. The Company does not design, manufacture or market semiconductor products under its own brand name, ensuring that it does not compete directly with its customers. Today, TSMC is the world's largest semiconductor foundry, manufacturing 9,275 different products using 249 distinct technologies for 449 different customers in 2016.

With such a large and diverse global customer base, TSMC-manufactured semiconductors are used in a wide variety of applications covering various segments of the computer, communications, consumer, industrial and standard semiconductor markets. Such strong diversification helps to smooth fluctuations in market demand, which, in turn, leads to higher levels of capacity utilization and profitability.

Annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries reached above 10 million 12-inch equivalent wafers in 2016. These facilities include three 12-inch wafer GIGAFAB® facilities, four 8-inch wafer fabs, and one 6-inch wafer fab in Taiwan, as well as two 8-inch wafer fabs at wholly owned subsidiaries: WaferTech in the United States and TSMC China Company Limited.

In March 2016, TSMC and the municipal government of Nanjing, China signed an investment agreement affirming that TSMC will make an investment to establish TSMC Nanjing Company Limited, a wholly-owned subsidiary managing a 12-inch wafer fab and a design service center. Planned capacity is 20,000 12-inch wafers per month. The facility is scheduled to commence production of 16nm process technology in the second half of 2018. The purpose is to provide closer support to customers as well as expand TSMC's market share and business opportunities in China in step with the rapid growth of the Chinese semiconductor market over the last several years.

TSMC provides customer service through its account management and engineering services offices in North

America, Europe, Japan, China, South Korea and India. The Company employed about 47,000 people at the end of 2016.

The Company is listed on the Taiwan Stock Exchange (TWSE) under ticker number 2330, and its American Depositary Shares (ADSs) are traded on the New York Stock Exchange (NYSE) under the symbol TSM.

2.2 Market/Business Summary

2.2.1 TSMC Achievements

In 2016, TSMC maintained its leading position in the total foundry segment of the global semiconductor industry, with an estimated market share of 56%, despite intense competition from both established players and relatively new entrants to the business.

Leadership in advanced process technologies is a key factor in the Company's strong market position. In 2016, 54% of TSMC's wafer revenue came from manufacturing processes with geometries of 28nm and below.

With TSMC's focus on customer trust, the Company strengthened its Open Innovation Platform® (OIP) initiative in 2016 with additional services. During the 2016 Open Innovation Platform® Ecosystem Forum, held in September in San Jose, California, and in October in Beijing, the Company revealed 7nm FinFET Reference Flow (both full-chip and IP design), which highlighted the success of OIP-enabled design. Both forums were well attended by customers and ecosystem partners and demonstrated the value of collaboration through OIP to foster innovation.

TSMC offers the foundry segment's widest technology portfolio and continues to invest in advanced technologies and specialty technologies, which are key differentiators vis-à-vis our competitors and provide customers more added value.

Technologies that the Company either developed or introduced in 2016 include:

Logic Technology

- 7nm FinFET (Fin field-effect transistor) technology made good developmental progress. Risk production of this technology is planned in April 2017. A very fast yield ramp-up is expected as more than 95% of tools for 7nm FinFET are compatible with those for 10nm FinFET. Compared to 10nm FinFET, 7nm FinFET offers approximately a 25% speed improvement or a 35% power reduction. In addition, 7nm FinFET can be optimized for mobile applications and high-performance computing devices.
- 10nm FinFET technology began production ramp-up in the fourth quarter of 2016 and started shipments in the first quarter of 2017. Thanks to its aggressive geometric shrinkage, this technology provides excellent density/cost benefits. It can be of use to customers in performance-driven market segments, including mobile, server and graphics.
- 16nm FinFET Plus technology (16FF+) received over 50 product tape-outs in 2016, bringing the total of product tape-outs to over 90 since this technology entered volume production in 2015. And most of them achieved first-time silicon success. This technology is aimed at customers in high-performance market segments, including mobile, server and graphics. The cost-effective 16nm FinFET Compact technology (16FFC) started volume production in the first quarter of 2016. 16FFC can maximize die cost scaling by incorporating optical shrink and process simplification at the same time. In addition, the development of 12nm FinFET Compact technology (12FFC) is progressing smoothly. This technology, which drives die size and power consumption to the best levels of the foundry's 16/14nm technology, is expected to enter volume production in the second half of 2017. Both 16FFC and 12FFC can satisfy customers in mainstream and ultra-low-power (ULP) market segments, including low-end to mid-range mobile phones, consumer electronics, digital TV and the IoT (internet of things). With innovative structures, 16FFC and 12FFC can also be used in more advanced applications, including high-end mobile and networking.
- 28nm High Performance Compact (28HPC) technology led the way in mainstream smartphones, DTVs, storage and SoC applications. 28HPC enables smaller die size circuit designs, less over-design and extraordinary power reduction with

- excellent process control and optimized design rules.
- 28nm High Performance Compact Plus (28HPC+) technology provided further performance enhancement or power reduction in mainstream smartphones, DTVs, storage, audio and SoC applications. Compared to 28HPC, 28HPC+ improves device performance by 15% or reduces leakage by 50%. 28HPC+ also enables low Vdd (voltage drain) designs in ULP applications for the IoT market. In addition, this process is seamlessly applicable to the 28nm ecosystem, accelerating time-to-market for customers.
- 40nm ULP and RF technologies started production in the first quarter of 2016 for the IoT and wearable devices related applications, such as wireless connectivity, application processors and sensor hub applications.
- 55nm Ultra-Low Power (55ULP) technology went into production, with more than 10 customers having already taped out using this technology. Compared to 55nm Low Power (55LP) process, 55ULP can significantly increase battery life for IoT applications. In addition, it integrates RF and eFlash (embedded flash) to simplify customers' SoC designs.

Specialty Technology

- 16FFC foundation IPs passed the Automotive Electronic Council AEC-Q100 Grade-1 qualification and were certified for functional safety standard ISO 26262 ASIL-B. In addition, TSMC 9000A was introduced for automotive IP management to complete the automotive ecosystem with third-party IP vendors.
- 16FFC RF technology started production in the first quarter of 2016. This technology supports wireless connectivity applications, including smartphones, wireless local area networks (WLAN), and fifth generation (5G) mobile networks.
- 28nm RF (28HPC RF and 28HPC+ RF) technologies offered extreme high-frequency devices, reliable model and comprehensive design support for wireless components in smartphone, automotive and IoT markets.
- 40nm eFlash started volume production in the first quarter of 2016 for applications such as high-endurance security MCU (microcontroller unit), wireless MCU, and high-performance MCU, as well as IoT devices.
- 40nm ULP eFlash was developed and started volume production in the second half of 2016 for applications such as wireless MCU, IoT devices, wearable devices and high-performance MCU.

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- 40nm high-voltage technology was qualified with 6V and 8V offerings for top-end smartphone LCD and AMOLED (active matrix organic LED) display drivers. This technology can improve display quality and reduce power consumption significantly.
- 55nm eFlash technologies passed AEC-Q100 qualification for automotive and started volume production in the first quarter of 2016 for automotive applications such as body control module (BCM), electric power steering (EPS) and electric vehicles (EV)/hybrid electric vehicles (HEV).
- CIS NIR+ (CMOS image sensor near infra-red plus) technology was successfully developed for higher (2X~3X) NIR quantum efficiency. This technology could enable depth sensing for the AR/VR (augmented reality/virtual reality) market and optical authentication for the smartphone market.
- 0.13 μ m Bipolar-CMOS-DMOS (BCD) process started volume production on both 8-inch and 12-inch wafers in 2016. This process in 12-inch fabs extended qualification for AEC-Q100 Grade-0 in the first half of 2015.
- 0.18 μ m BCD third generation passed process validation by customers. This technology, which provides superior cost competitiveness compared to the second generation, started production in the second half of 2016.
- 0.5 μ m GaN (gallium nitride) on silicon 650V E-HEMT (enhanced-mode high electron mobility transistor), 650V D-MISFET (depletion-mode metal-insulator-semiconductor field-effect transistor), 100V E-HEMT and 30V D-HEMT (depletion-mode high electron mobility transistor) processes were qualified for discrete power applications. GaN on silicon technology offers high power density and efficiency in power applications.
- Successfully developed Si-pillar WLCSP (wafer level chip scale packaging) technology, which can be applied to customers' CMOS-MEMS (micro-electromechanical systems) motion sensor SoC designs, creating the world's smallest packaging dimension, as small as 1.1mm by 1.3mm.

Advanced Packaging Technology

- Integrated Fan-Out Package on Package (InFO-PoP) technology that integrates 16nm SoC and DRAM for advanced mobile products began volume production in the second quarter of 2016. It enables a thinner package, 10% less thermal resistance, more logic I/Os, and 5 to 10% higher maximum operating frequency for application processor.

- CoWoS[®] (chip on wafer on substrate) XL technology homogeneously integrating multiple 20nm logic chips and heterogeneously integrating 16nm SoC plus four stacks of 4-hi (4 high) second generation high bandwidth memory (HBM2) began production in the first half of 2016. Integration of 16nm SoC, larger interposer (>1400mm²) and more than four 8-hi (8 high) HBM2 stacks is expected to be developed in 2017.
- Fine pitch (80 μ m) BoT (Bump-on-Trace) Cu bump for flip chip packaging on \geq 16nm silicon continued volume production in 2016. Cu bump on 10nm silicon was qualified for production start-up in 2017. Volume production also continued on \geq 28nm silicon in WLCSP technologies for high-end smartphone applications in 2016. 16nm WLCSP qualification was started and is expected to be completed in the first half of 2017.

2.2.2 Market Overview

TSMC estimates that the worldwide semiconductor market in 2016 was US\$357 billion in revenue, representing 1% year-over-year growth, continuing the flattish growth in 2015. In the foundry sub-segment of the semiconductor industry, total revenue was US\$47 billion in 2016, representing 8% YoY growth.

2.2.3 Industry Outlook, Opportunities and Threats

Industry Demand and Supply Outlook

The increase in the foundry segment growth to 8% in 2016 from 4% in 2015 was driven mainly by healthier market and inventory replenishment.

TSMC forecasts the total semiconductor market to grow 4% in 2017. Over the longer term, driven by increasing semiconductor content in electronic devices, continuing market share gains by fabless companies, gradual increase of IDM outsourcing, and expanding in-house Application-Specific Integrated Circuits (ASIC) from system companies, the Company expects foundry segment revenue growth to be much stronger than the 3% compound annual growth rate projected for the total semiconductor industry from 2015 through 2020.

As an upstream supplier in the semiconductor supply chain, the foundry segment is tightly correlated with the market health of the three Cs, communications, computer, consumer, and the emerging IoT (Internet of Things).

• Communications

The communications sector, particularly the Smartphone segment, posted a 6% growth in unit shipments for 2016. Although the growth is slowing down, continuing transition to 4G/LTE and LTE-Advanced will bring about mid-single digit growth to the Smartphone market in 2017. Smartphones with increasing performance, longer battery life, and more intelligent features will continue to propel buying interests. The increasing popularity of low-end smartphones in emerging countries will also drive the growth of the sector.

Low-power IC is an essential requirement among handset manufacturers. The SoC design for more optimized cost, power and form factor (device footprint and thickness), plus the appetite for higher performance to run complex software and higher resolution video will continue to accelerate the migration to advanced process technologies, in which TSMC is already the leader.

• Computer

After an 8% decline in 2015, the computer sector's unit shipments dropped 6% YoY in 2016. The decline was due to prolonged replacement cycle and consumer usage moving towards mobile computing.

The personal computer market is expected to decline by mid-single digit percentage in 2017. Increasing variety (e.g. Convertible, Ultrabook and Chromebook), the business adoption of Windows 10, and consumer replacements of aging PCs, however, are expected to help buoy PC demand.

In terms of process technologies used in computers, requirements of lower power, higher performance and the integration of key computer components such as CPU, GPU, Chipset, etc., should drive demand for product refresh towards leading process technologies.

• Consumer

The consumer sector's unit shipments declined 5% in 2016 comparing to 2015. Set-top boxes and TV game consoles showed positive growth, while the rest of the sector – TVs, MP3 players, digital cameras and hand-held game consoles – continued to decline due to unsettled environment in Eurozone and foreign exchange issues, as well as functional cannibalization by smartphones.

Although consumer electronics will continue to decline in 2017, TV game consoles, 4K (UHD) TVs, and over-the-top (OTT) set-top boxes should achieve high growth within the sector. TSMC will be able to capture these trends with advanced technology offerings.

• IoT

The Internet of Things (IoT) is taking shape as the “next big thing,” since more and more devices are being connected to the Internet. The IoT will have 10X greater installed unit potential than the smartphone will have in 2025. Applications and products benefiting from IoT related technologies include smart wearables, home robots, smart meters, smart manufacturing, self-driving cars, and so on. These applications and products will require much longer battery life, diversified sensors and low-power wireless connections, which will challenge technology development in new ways. TSMC's ultra-low-power logic and RF solutions and diversified sensing technologies will lead the way for this future growth.

Supply Chain

The electronics industry consists of a long and complex supply chain, the elements of which are highly dependent and correlated with each other. At the upstream IC manufacturing level, IC vendors need to have sufficient and flexible supply to handle the demand dynamics. The foundry vendors are playing an important role to ensure the health of the supply chain. As a leader in the foundry segment, TSMC provides leading technologies and large-scale capacity to complement the innovations created along the downstream chain.

2.2.4 TSMC Position, Differentiation and Strategy

Position

TSMC is the worldwide semiconductor foundry leader for both advanced and specialty process technologies, commanding a 56% market share in 2016. Net revenue by geography, based mainly on the country in which customers are headquartered, was: 65% from North America; 15% from the Asia Pacific region, excluding China and Japan; 9% from China; 6% from Europe, the Middle East and Africa; and 5% from Japan. Net revenue by end-product application was: 8% from the computer sector, 62% from communications, 9% from consumer products, and 21% from industrial and standard products.

Differentiation

TSMC's leadership position is based on three defining competitive strengths and a business strategy rooted in the Company's heritage. The Company distinguishes itself from the competition through its technology leadership, manufacturing excellence and customer trust.

As a technology leader, TSMC is consistently first among dedicated foundries to provide next-generation, leading-edge technologies. The Company has also established its leadership on more mature technology nodes by applying the lessons learned on leading-edge technology development to enrich its specialty technologies to more advanced process nodes. Beyond process technology, TSMC has established frontend and backend integration capabilities that result in faster time-to-production and create the best power, performance and area sweet spot.

TSMC has gained manufacturing acclaim for its industry-leading management and is extending that leadership through its Open Innovation Platform® and Grand Alliance initiatives. The TSMC Open Innovation Platform® initiative hastens the pace of innovation in the semiconductor design community and among its ecosystem partners, as well as the Company's IP, design implementation and design for manufacturing capabilities, process technology and backend

services. A key element is a set of ecosystem interfaces and collaborative components initiated and supported by TSMC that more efficiently empower innovation throughout the supply chain and drive the creation and sharing of new revenue and profits. The TSMC Grand Alliance is one of the most powerful forces for innovation in the semiconductor industry, bringing together customers, electronic design automation (EDA) partners, IP partners, and key equipment and material suppliers at a new, higher level of collaboration. Its objective is to help customers, alliance members and TSMC win business and stay competitive.

The foundation for customer trust is a commitment TSMC made when it opened for business in 1987: to never compete with its customers. As a result, TSMC has never owned or marketed a single semiconductor product design, but instead has focused all of its resources on becoming the trusted foundry for its customers.

Strategy

TSMC is confident that its differentiating strengths will enable it to prosper from the foundry segment's many attractive growth opportunities. In light of the rapid growth in four major markets, namely mobile, high-performance computing, automotive electronics, and the Internet of things, and the fact that focus of customer demand is shifting from process-technology-centric to product-application-centric, TSMC has constructed four different technology platforms to provide customers with the most comprehensive and competitive logic process technologies, specialty technologies, IPs, and packaging and testing technologies to shorten customers' time-to-design and time-to-market.

Mobile platform: TSMC will offer leading 7nm FinFET, 10nm FinFET, 16FF+, 20nm SoC, 28nm High Performance (HP), and 28nm High Performance Mobile (28HPM) logic process technologies as well as comprehensive IPs for high-end product applications to further enhance chip performance, reduce power consumption, and decrease chip size. For low-end to mid-range product applications, TSMC will offer 12FFC, 16FFC, 28nm Low Power (LP), 28nm High Performance Low Power

(HPL), 28HPC, 28HPC+, and 22ULP logic process technologies in addition to comprehensive IPs to satisfy customer needs for high-performance and low-power chips. Furthermore, for high-end or low- to mid-level product applications, TSMC also offers the most competitive, leading-edge specialty technologies, including RF, embedded flash memory, emerging memory technologies, power management, sensors, and display chips and advanced packaging technologies such as the leading integrated fan-out (InFO) technology.

High-performance computing platform: TSMC will offer customers leading 7nm, 16nm FinFET and 28nm logic process technologies, as well as comprehensive IPs, including high speed interconnect IPs, to meet customers' high performance computing and transmission requirements. TSMC also offers multiple advanced packaging technologies such as CoWoS® and 3D IC technologies to enable homogeneous and heterogeneous chip system integration to meet customers' high performance, low power, and smaller system footprint requirements. TSMC will continue to optimize our high performance computing platform offerings to help customers capture market growth driven by massive data and applications, including data analytics, artificial intelligence, and 5G wireless communications.

Automotive electronics platform: TSMC will offer leading 7nm FinFET, 16nm FinFET, 28nm, and 40nm logic process technologies, various leading and competitive specialty technologies in RF, embedded flash memory, sensors, multiple power management technologies that pass the AEC-Q100 Grade-0 qualifications, and many advanced packaging technologies.

IoT platform: TSMC will provide customers with leading ULP logic process technology options, from 16nm, 12nm, 28nm, 40nm to 55nm, the most competitive and leading-edge specialty technologies in RF, embedded flash memory, emerging memory, sensors, and display chips, as well as, multiple advanced packaging technologies including the leading InFO technology.

TSMC continually strengthens its core competitiveness and deploys both short-term and long-term technology and business development plans, and assists customers in taking on the challenges of short product cycles and intense competition in the electronic products market to meet ROI and growth objectives.

• Short-Term Semiconductor Business Development Plan

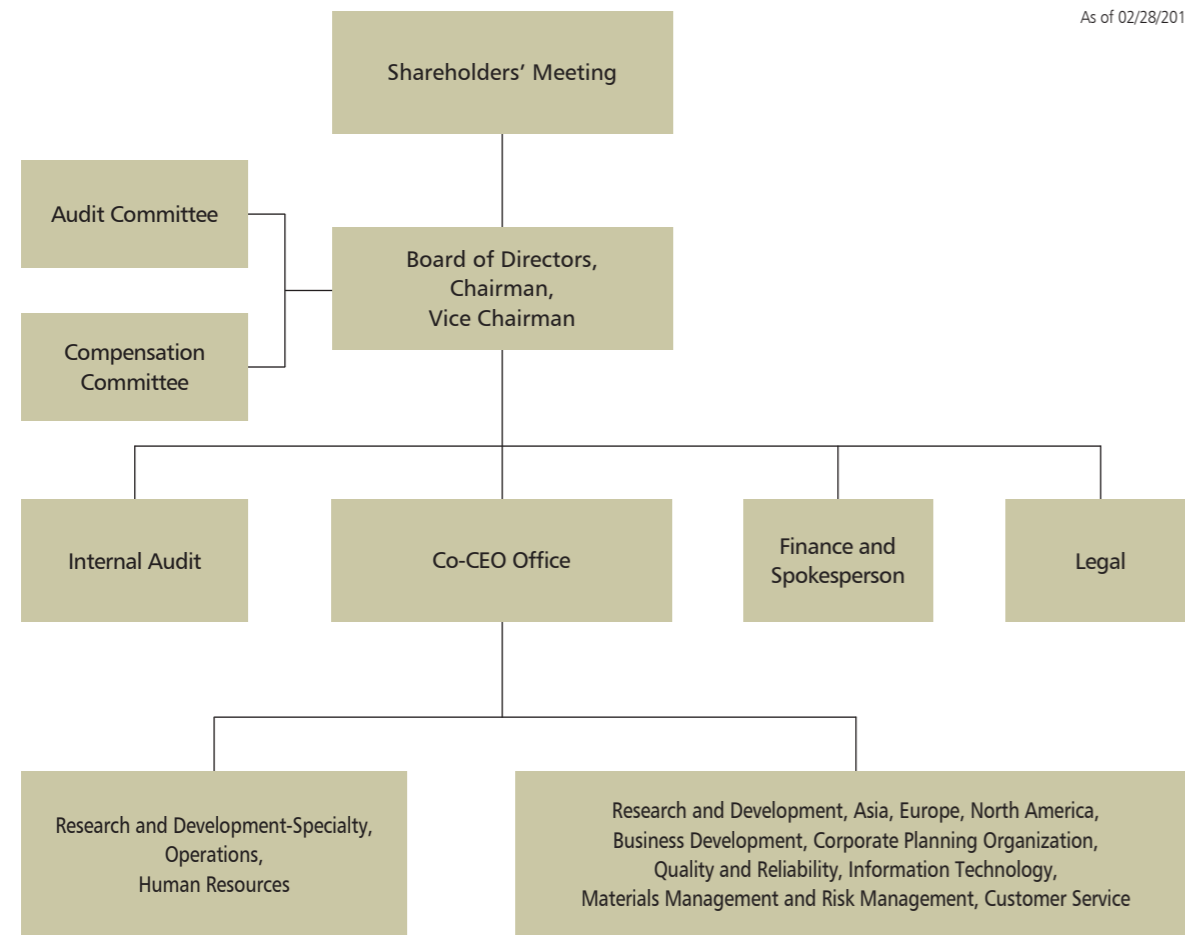
1. Substantially ramp up the business and sustain advanced technology market share by increased capacity investment.
2. Maintain mainstream technology market share by expanding business to new customers and market segments with off-the-shelf technologies.
3. Continue to enhance the competitive advantages of TSMC's platforms in mobile, high-performance computing, automotive electronics, and IoT design ecosystems so as to expand TSMC's dedicated foundry services in these product applications.
4. Further expand TSMC's business and service infrastructure into emerging and developing markets.

• Long-Term Semiconductor Business Development Plan

1. Continue developing leading-edge technologies at a pace consistent with Moore's Law.
2. Broaden specialty business contributions by further developing derivative technologies.
3. Provide more integrated services, covering system-level integration design, design technology definition, design tool preparation, wafer processing, and backend services, all of which deliver more value to customers through optimized solutions.

2.3 Organization

2.3.1 Organization Chart



2.3.2 Major Corporate Functions

Operations

- Operations of all fabs including in Taiwan and overseas; product development, manufacturing technology development, and backend technology development and production

Human Resources

- Human resources management and organizational development, as well as proprietary information protection and physical security management

Research and Development

- Advanced and specialty technology development and exploratory research, as well as design and technology platform development

Asia

- Sales, market development, field technical support and service for customers in Asia

Europe

- Technical marketing, field technical support and service for customers in Europe

North America

- Sales, market development, field technical support and service for customers in North America

Business Development

- Business development for electronic products, identification of new applications, development of markets for specialty technology, exploration and development of new markets, and strengthening customer relations, as well as managing the Company's brand

Corporate Planning Organization

- Planning for operational resources, as well as for production and demand; the integration of business processes, corporate pricing, market analysis and forecasting

Quality and Reliability

- Assurance of the quality and reliability of the Company's products via: resolution of reliability issues at development stage, improvement and management of production quality, solutions for customers' quality related issues, services for advanced materials and failure analysis

Information Technology

- Integration of the Company's technology and business IT systems; infrastructure development, communication services and assurance of IT security and service quality

Materials Management and Risk Management

- Procurement, warehousing, import and export, and logistics support; also environmental protection, industrial safety, occupational health, and risk management

Customer Service

- Support and service for customers in Asia, Europe, and North America

Internal Audit

- Inspection and review of TSMC's internal control system, its adequacy in design and effectiveness in operation with independent risk assessment to ensure compliance with TSMC's policies and procedures as well as with external regulations

Finance and Spokesperson

- Corporate finance, accounting and corporate communications; the head of the organization also serves as company spokesperson

Legal

- Corporate legal affairs including regulatory compliances, commercial transactions, patents and management of other intellectual properties, litigation, etc.

2.4 Board Members

2.4.1 Information Regarding Board Members

As of 02/28/2017

Title/Name	Gender	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shareholding When Elected		Current Shareholding		Spouse & Minor Shareholding		Selected Education, Past Positions & Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares	%	Shares	%	Shares	%		
Chairman Morris Chang	Male	U.S.A.	06/09/2015	06/08/2018	12/10/1986	125,137,914	0.48%	125,137,914	0.48%	135,217	0.00%	Bachelor Degree in Mechanical Engineering, MIT Master Degree in Mechanical Engineering, MIT Ph.D. in Electrical Engineering, Stanford University Former Group Vice-President, Texas Instruments Inc. Former President & COO, General Instrument Corporation Former Chairman, Industrial Technology Research Institute Former CEO, TSMC Member of National Academy of Engineering Life Member Emeritus of MIT Corporation Fellow of the Computer History Museum Laureate of the Industrial Technology Research Institute	None
Vice Chairman F.C. Tseng	Male	R.O.C.	06/09/2015	06/08/2018	05/13/1997	34,472,675	0.13%	34,472,675	0.13%	132,855	0.00%	Bachelor Degree in Electrical Engineering, National Chengkung University Master Degree in Electrical Engineering, National Chiao Tung University Ph.D. in Electrical Engineering, National Chengkung University Honorary Ph.D., National Chiao Tung University Former President, Vanguard International Semiconductor Corp. Former President, TSMC Former Deputy CEO, TSMC Former Director, National Culture and Arts Foundation, R.O.C. Chairman, TSMC Education and Culture Foundation	Chairman of: - TSMC China Company Ltd. - Global UniChip Corp. Vice Chairman, Vanguard International Semiconductor Corp. Independent Director, Chairman of Audit Committee & Compensation Committee member, Acer Inc.
Director National Development Fund, Executive Yuan (Note 1) Representative: Johnsee Lee	Male	R.O.C.	06/09/2015	06/08/2018	12/10/1986 08/06/2010 (Note 2)	1,653,709,980	6.38%	1,653,709,980	6.38%	-	-	Ph.D. in Chemical Engineering, Illinois Institute of Technology MBA, University of Chicago Graduate of Harvard Business School's Advanced Management Program Former Principal Investigator, Argonne National Laboratory Former Senior Manager, Johnson Matthey Inc. Former President, Industrial Technology Research Institute Former Chairman, Development Center for Biotechnology Managing Director, Development Center for Biotechnology Honorary Chairman, Taiwan Bio Industry Organization	CEO, Personal Genomics, Inc. Independent Director of: - Far Eastern New Century Corp. - Zhen Ding Technology Holding Ltd. - Everlight Electronics Co., Ltd. - San Fu Chemical Co., Ltd.
Independent Director Sir Peter Leahy Bonfield	Male	UK	06/09/2015	06/08/2018	05/07/2002	-	-	-	-	-	-	Bachelor Degree in Engineering, Loughborough University Honours Degree in Engineering, Loughborough University Former Chairman and CEO, ICL Plc Former CEO and Chairman of the Executive Committee, British Telecommunications Plc Former Vice President, the British Quality Foundation Fellow of the Royal Academy of Engineering Chair of Council and Senior Pro-Chancellor, Loughborough University, UK	Chairman of: - NXP Semiconductors N.V., the Netherlands - Global Logic Inc., U.S.A. Member, The Longreach Group Advisory Board Board Mentor, CMi Senior Advisor to: - Alix Partners, London - G3 Good Governance Group, London.
Independent Director Stan Shih	Male	R.O.C.	06/09/2015	06/08/2018	04/14/2000	1,480,286	0.01%	1,480,286	0.01%	16,116	0.00%	BSEE, National Chiao Tung University MSEE, National Chiao Tung University Honorary EE Ph.D., National Chiao Tung University Honorary Doctor of Technology, The Hong Kong Polytechnic University Honorary Fellowship, University of Wales, Cardiff, UK Honorary Doctor of International Law, Thunderbird, American Graduate School of International Management, U.S.A. Co-Founder, Chairman Emeritus, Acer Group Former Chairman & CEO, Acer Group Former Chairman, National Culture and Arts Foundation, R.O.C. Director, Public Television Service Foundation, R.O.C. Council member of Asian Corporate Governance Associate (ACGA) Chairman of Stans Foundation	Director & Honorary Chairman, Acer Inc. Director of: - Qisda Corp. - Wistron Corp. - Nan Shan Life Insurance Co., Ltd. - Egis Technology Inc. - Digitimes Inc. - Chinese Television System Inc.

(Continued)

Title/Name	Gender	Nationality or Place of Registration	Date Elected	Term Expires	Date First Elected	Shareholding When Elected		Current Shareholding		Spouse & Minor Shareholding		Selected Education, Past Positions & Current Positions at Non-profit Organizations	Selected Current Positions at TSMC and Other Companies
						Shares	%	Shares	%	Shares	%		
Independent Director Thomas J. Engibous	Male	U.S.A.	06/09/2015	06/08/2018	06/10/2009	-	-	-	-	-	-	Bachelor Degree in Electrical Engineering, Purdue University Master Degree in Electrical Engineering, Purdue University Honorary Doctorate in Engineering, Purdue University Former Executive Vice President and President of the Semiconductor Group, Texas Instruments Inc. Former President and CEO, Texas Instruments Inc. Former Chairman of the Board, Texas Instruments Inc. Former Chairman of the Board of Catalyst Former Chairman of the Board of J.C. Penney Company, Inc. Former Lead Director, J.C. Penney Company, Inc. Member of National Academy of Engineering Member of Texas Business Hall of Fame Honorary Director of Catalyst Honorary Trustee, Southwestern Medical Foundation	None
Independent Director Kok-Choo Chen	Female	R.O.C.	06/09/2015	06/08/2018	06/09/2011	-	-	-	-	5,120	0.00%	Inns of Court School of Law, England Barrister-at-law, England Advocate & Solicitor, Singapore Attorney-at-law, California, U.S.A. Lawyer, Tan, Rajah & Cheah, Singapore, 1969-1970 Lawyer, Sullivan & Cromwell, New York, U.S.A., 1971-1974 Lawyer, Heller, Erhman, White & McAuliffe, San Francisco, California, U.S.A., 1974-1975 Partner, Ding & Ding Law Offices, Taiwan, 1975-1988 Partner, Chen & Associates Law Offices, Taiwan, 1988-1992 Former Vice-President, Echo Publishing, Taiwan, 1992-1995 Former President, National Culture and Arts Foundation, R.O.C., 1995-1997 Former Senior Vice-President & General Counsel, TSMC, 1997-2001 Founder & Executive Director of Taipei Story House, 2003-2015 Former Advisor, Executive Yuan, R.O.C., 2009-2016 Former Director, National Culture and Arts Foundation, R.O.C., 2011-2016 Former Chairman, National Performing Arts Center, 2014-January 2017 Lecturer, Nanyang University, Singapore, 1970-1971 Associate Professor, Soochow University, 1981-1998 Chair Professor, National Tsing Hua University, 1999-2002 Professor, National Chengchi University, 2001-2004 Professor, Soochow University, 2001-2008 Founder and Executive Director, Museum207 (located in Taipei) Director, Republic of China Female Cancer Foundation	None
Independent Director Michael R. Splinter	Male	U.S.A.	06/09/2015	06/08/2018	06/09/2015	-	-	-	-	-	-	Bachelor and Master Degrees in Electrical Engineering, University of Wisconsin Madison Honorary Ph.D. in Engineering, University of Wisconsin Madison Former Executive Vice President of Technology and Manufacturing group, Intel Corporation Former Executive Vice President of Sales and Marketing, Intel Corporation Former CEO, Applied Materials, Inc. Former Chairman, Applied Materials, Inc. Director, Silicon Valley Leadership Group Director, Semiconductor Equipment and Materials International (SEMI) Director, University of Wisconsin Foundation	Director of: - The NASDAQ OMX Group, Inc. - Pica8, Inc. General Partner, WISC Partners LP

Remarks:

1. No member of the Board of Directors held TSMC shares by nominee arrangement.
2. No member of the Board of Directors had a spouse or relative within two degrees of consanguinity serving as a manager or director at TSMC.

Note 1: Major Shareholder of TSMC's Director that is an Institutional Shareholder.

Director that is an Institutional Shareholder of TSMC	Top 10 Shareholders
National Development Fund, Executive Yuan	Not Applicable

Major Institutional shareholders of National Development Fund: Not Applicable.

Note 2: Mr. Johnsee Lee was appointed as the representative of National Development Fund on August 6, 2010.

2.4.2 Remuneration Paid to Directors (Note 1)

Unit: NT\$ thousands

Title/Name	Director's Remuneration								Compensation Earned by a Director Who is an Employee of TSMC or of TSMC's Consolidated Entities								Total Compensation (A+B+C+D+E+F+G) as a % of 2016 Net Income (Note 4)		Compensation Paid to Directors from Non-consolidated Affiliates (J)		
	Base Compensation (A)		Severance Pay and Pensions (B) (Note 2)		Compensation to Directors (C)		Allowances (D) (Note 3)		Total Remuneration (A+B+C+D) as a % of 2016 Net Income		Base Compensation, Bonuses, and Allowances (E)		Severance Pay and Pensions (F) (Note 2)		Employees' Profit Sharing Bonus (G)						
	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC		From All Consolidated Entities			From TSMC	From All Consolidated Entities
															Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)			
Chairman Morris Chang	22,314	22,314	592	592	286,690	286,690	1,941	1,941	0.0932%	0.0932%	-	-	-	-	-	-	-	-	0.0932%	0.0932%	-
Vice Chairman F.C. Tseng	12,585	12,585	334	334	9,600	9,600	1,778	1,778	0.0073%	0.0073%	-	-	-	-	-	-	-	-	0.0073%	0.0073%	4,512
Independent Director Sir Peter Leahy Bonfield	-	-	-	-	15,514	15,514	-	-	0.0046%	0.0046%	-	-	-	-	-	-	-	-	0.0046%	0.0046%	-
Independent Director Stan Shih	-	-	-	-	12,000	12,000	-	-	0.0036%	0.0036%	-	-	-	-	-	-	-	-	0.0036%	0.0036%	-
Independent Director Thomas J. Engibous	-	-	-	-	15,514	15,514	-	-	0.0046%	0.0046%	-	-	-	-	-	-	-	-	0.0046%	0.0046%	-
Independent Director Kok-Choo Chen	-	-	-	-	12,000	12,000	-	-	0.0036%	0.0036%	-	-	-	-	-	-	-	-	0.0036%	0.0036%	-
Independent Director Michael R. Splinter	-	-	-	-	15,514	15,514	-	-	0.0046%	0.0046%	-	-	-	-	-	-	-	-	0.0046%	0.0046%	-
Director National Development Fund, Executive Yuan Representative: Johnsee Lee	-	-	-	-	9,600	9,600	-	-	0.0029%	0.0029%	-	-	-	-	-	-	-	-	0.0029%	0.0029%	-
Total	34,899	34,899	926	926	376,432	376,432	3,719	3,719	0.1244%	0.1244%	-	-	-	-	-	-	-	-	0.1244%	0.1244%	4,512

Note 1: Remuneration policies, standards/packages, procedures, the linkage to operating performance and future risk exposure: The base compensation for the Chairman, Vice-Chairman and directors are determined in accordance with the procedures set forth in TSMC's Articles of Incorporation. The Articles of Incorporation also provides that the compensation to directors shall be no more than 0.3% of annual profits and directors who also serve as executive officers of TSMC are not entitled to receive compensation to directors. The distribution of compensation to directors shall be made in accordance with TSMC's "Rules for Distribution of Compensation to Directors".

Note 2: Pensions funded/paid according to applicable law.

Note 3: The above-mentioned figures include expenses for Company cars and gasoline reimbursement, but do not include compensation paid to Company drivers (totaled NT\$4,815 thousand).

Note 4: Total remuneration and compensation of TSMC and all consolidated entities paid to TSMC's directors in 2015 were NT\$394,468 thousand, accounting for 0.13% of 2015 net income.

2.5 Management Team

2.5.1 Information Regarding Management Team

As of 02/28/2017

Title Name	Gender	Nationality	On-board Date (Note 1)	Shareholding		Spouse & Minor		TSMC Shareholding by Nominee Arrangement (Shares)		Education & Selected Past Positions	Selected Current Positions at Other Companies	Managers Who are Spouses or within Second-degree Relative of Consanguinity to Each Other		
				Shareholds	%	Shareholds	%	Shareholds	%			Title	Name	Relation
President and Co-Chief Executive Officer Mark Liu	Male	R.O.C.	11/15/1993	12,977,114	0.05%	-	-	-	-	Ph.D., Electrical Engineering & Computer Science, University of California, Berkeley, U.S. Executive Vice President and Co-Chief Operating Officer, TSMC Senior Vice President, Operations, TSMC Senior Vice President, Advanced Technology Business, TSMC President, Worldwide Semiconductor Manufacturing Corp.	None	None	None	None
President and Co-Chief Executive Officer C.C. Wei	Male	R.O.C.	02/01/1998	7,179,207	0.03%	261	0.00%	-	-	Ph.D., Electrical Engineering, Yale University, U.S. Executive Vice President and Co-Chief Operating Officer, TSMC Senior Vice President, Business Development, TSMC Senior Vice President, Mainstream Technology Business, TSMC Senior Vice President, Chartered Semiconductor Manufacturing Ltd.	Director, TSMC subsidiary	None	None	None
Senior Vice President and Chief Information Officer Information Technology, Materials Management and Risk Management Stephen T. Tso	Male	R.O.C.	12/16/1996	12,897,064	0.05%	-	-	-	-	Ph.D., Materials Science & Engineering, University of California, Berkeley, U.S. President, WaferTech, LLC Senior Vice President, Operations, TSMC General Manager of CVD Products, Applied Material, Inc.	Director, TSMC subsidiary	None	None	None
Senior Vice President, Chief Financial Officer and Spokesperson Finance Lora Ho	Female	R.O.C.	06/01/1999	4,481,080	0.02%	2,230,268	0.01%	-	-	Master, Business Administration, National Taiwan University, Taiwan Senior Director, Accounting, TSMC Vice President & CFO, TI-Acer Semiconductor Manufacturing Corp.	Director and/or Supervisor, TSMC subsidiaries Director, TSMC affiliates President, TSMC subsidiaries	None	None	None
Senior Vice President Research and Development/Technology Development Wei-Jen Lo	Male	R.O.C.	07/01/2004	1,464,127	0.01%	-	-	-	-	Ph.D., Solid State Physics and Surface Chemistry, University of California, Berkeley, U.S. Vice President, Research and Development, TSMC Vice President, Operations/Manufacturing Technology, TSMC Vice President, Advanced Technology Business, TSMC Vice President, Operation II, TSMC Director, Advanced Technology Development and CTM Plant Manager, Intel Corp.	None	None	None	None
Senior Vice President of TSMC and President of TSMC North America Rick Cassidy	Male	U.S.A.	11/14/1997	-	-	-	-	-	-	Bachelor, Engineering Technology, United States Military Academy at West Point, U.S. Vice President of TSMC North America Account Management	Director, TSMC subsidiary	None	None	None
Senior Vice President Operations/Product Development Y.P. Chin (Note 2)	Male	R.O.C.	01/01/1987	6,971,122	0.03%	2,194,107	0.01%	-	-	Master, Electrical Engineering, National Cheng Kung University, Taiwan Vice President, Advanced Technology and Business, TSMC Senior Director, Product Engineering & Services, TSMC	None	None	None	None
Senior Vice President Research and Development/Technology Development Y.J. Mii (Note 2)	Male	R.O.C.	11/14/1994	1,000,419	0.00%	-	-	-	-	Ph.D., Electrical Engineering, University of California, Los Angeles, U.S. Senior Director, R&D Platform I Division, TSMC	None	None	None	None
Vice President Operations/Affiliate Fabs M.C. Tzeng	Male	R.O.C.	01/01/1987	7,405,595	0.03%	-	-	-	-	Master, Applied Chemistry, Chungyuan University, Taiwan Vice President, Mainstream Technology Business, TSMC Senior Director, Fab 2 Operation, TSMC	Director, TSMC subsidiaries Director, TSMC affiliate	Deputy Director	M.J. Tzeng	Siblings
Vice President and Chief Technology Officer Research and Development/Corporate Research Jack Sun	Male	R.O.C.	06/02/1997	3,981,831	0.02%	-	-	-	-	Ph.D., Electrical Engineering, University of Illinois at Urbana-Champaign, U.S. Vice President, Research and Development, TSMC Senior Director, Logic Technology Division, TSMC Senior Manager of R&D, International Business Machines (IBM)	None	None	None	None
Vice President Quality and Reliability N.S. Tsai	Male	R.O.C.	03/01/2000	1,988,180	0.01%	1,103,253	0.00%	-	-	Ph.D., Material Science, Massachusetts Institute of Technology, U.S. Senior Director, Assembly Test Technology & Service, TSMC Vice President, Operations, Vanguard International Semiconductor Corp.	None	None	None	None
Vice President Operations/Mainstream Fabs and Manufacturing Technology J.K. Lin	Male	R.O.C.	01/01/1987	12,498,018	0.05%	1,048,387	0.00%	-	-	Bachelor, Science, National Changhua University of Education, Taiwan Senior Director, Mainstream Fabs, TSMC	Director, TSMC subsidiary Director, TSMC affiliate	None	None	None
Vice President Operations/300mm Fabs J.K. Wang	Male	R.O.C.	02/11/1987	2,553,947	0.01%	160,844	0.00%	-	-	Master, Chemical Engineering, National Cheng Kung University, Taiwan Senior Director, 300mm fab operations, TSMC	Director, TSMC subsidiary	None	None	None

(Continued)

Title Name	Gender	Nationality	On-board Date (Note 1)	Shareholding		Spouse & Minor		TSMC Shareholding by Nominee Arrangement (Shares)		Education & Selected Past Positions	Selected Current Positions at Other Companies	Managers Who are Spouses or within Second-degree Relative of Consanguinity to Each Other		
				Shareholds	%	Shareholds	%	Shareholds	%			Title	Name	Relation
Vice President Corporate Planning Organization Irene Sun	Female	R.O.C.	10/01/2003	420,709	0.00%	-	-	-	-	Ph.D., Materials Science and Engineering, Cornell University, U.S. Senior Director, Corporate Planning Organization, TSMC	None	None	None	None
Vice President Research and Development/Design and Technology Platform Cliff Hou	Male	R.O.C.	12/15/1997	352,532	0.00%	60,802	0.00%	-	-	Ph.D., Electrical Engineering, Syracuse University, U.S. Senior Director, Design and Technology Platform, TSMC	Director, TSMC subsidiaries Director, TSMC affiliate President, TSMC subsidiaries	None	None	None
Vice President Business Development Been-Jon Woo	Female	R.O.C.	04/30/2009	320,000	0.00%	51,000	0.00%	-	-	Ph.D., Chemistry, University of Southern California, U.S. Director of Business Development, TSMC Vice President of R&D, Grace Semiconductor Manufacturing Corp. Director of Technology Integration, Intel Corp.	None	None	None	None
Vice President and General Counsel Legal Sylvia Fang	Female	R.O.C.	03/20/1995	700,285	0.00%	419,112	0.00%	34,000	0.00%	Master of Comparative Law, School of Law, University of Iowa Attorney-at-law, Taiwan Associate General Counsel, TSMC Taiwan International Patent and Law Office (TIPL0)	Director and/or Supervisor, TSMC subsidiaries	None	None	None
Vice President Human Resources Connie Ma	Female	R.O.C.	06/01/2014	80,000	0.00%	-	-	-	-	EMBA, International Business Management, National Taiwan University Director of Human Resources, TSMC Senior Vice President of Global Human Resources, Trend Micro Inc.	None	None	None	None
Vice President Research and Development/Technology Development Y.L. Wang	Male	R.O.C.	06/01/1992	218,535	0.00%	1,135,529	0.00%	-	-	Ph.D., Electrical Engineering, National Chiao Tung University, Taiwan Vice President, Fab 14B operations, TSMC Senior Director, Fab 14B operations, TSMC	None	None	None	None
Vice President Research and Development/Integrated Interconnect & Packaging Douglas Yu (Note 3)	Male	R.O.C.	12/28/1994	225,000	0.00%	-	-	-	-	PhD, Materials Engineering, Georgia Institute of Technology, U.S. Senior Director of Integrated Interconnect & Packaging Division in R&D, TSMC	None	None	None	None
Vice President Research and Development/More-than-Moore Technologies Alexander Kalnitsky (Note 3)	Male	U.S.A.	06/15/2009	-	-	-	-	-	-	PhD, Electrical Engineering, Carleton University, Canada Senior Director of More-than-Moore Technologies Division in R&D, TSMC	None	None	None	None
Vice President Research and Development/Design and Technology Platform Kevin Zhang (Note 3)	Male	U.S.A.	11/01/2016	-	-	-	-	-	-	PhD, Electrical Engineering, Duke University, U.S. Vice President, Technology and Manufacturing Group, Intel Corp.	None	None	None	None

Note 1: On-board date means the official date joining TSMC.

Note 2: Mr. Y.P. Chin and Dr. Y.J. Mii were promoted to Senior Vice President, effective November 8, 2016.

Note 3: Dr. Douglas Yu, Dr. Alexander Kalnitsky and Dr. Kevin Zhang were promoted to Vice President, effective November 8, 2016.

2.5.2 Compensation Paid to President & Co-CEO and Vice Presidents (Note 1)

Unit: NT\$ thousands

Title	Name	Salary (A)		Severance Pay and Pensions (B) (Note 4)		Bonuses and Allowances (C) (Note 5)		Employees' Profit Sharing Bonus (D)				Total Compensation (A+B+C+D) as a % of 2016 Net Income (Note 6)		Compensation Received from Non-consolidated Affiliates
		From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC	From All Consolidated Entities	From TSMC		From All Consolidated Entities		From TSMC	From All Consolidated Entities	
								Cash	Stock (Fair Market Value)	Cash	Stock (Fair Market Value)			
President and Co-Chief Executive Officer	Mark Liu	8,118	8,118	252	252	103,709	103,709	101,588	-	101,588	--	0.064%	0.064%	-
President and Co-Chief Executive Officer	C.C. Wei	8,118	8,118	252	252	104,152	104,152	101,588	-	101,588	-	0.064%	0.064%	-
Senior Vice President, Chief Financial Officer and Spokesperson Finance	Lora Ho	5,222	5,222	162	162	49,118	49,118	47,318	-	47,318	-	0.030%	0.030%	-
Senior Vice President and Chief Information Officer Information Technology, Materials Management and Risk Management	Stephen T. Tso													
Senior Vice President Research and Development/ Technology Development	Wei-Jen Lo													
Senior Vice President of TSMC and President of TSMC North America	Rick Cassidy													
Senior Vice President Operations/Product Development	Y.P. Chin (Note 2)													
Senior Vice President Research and Development/ Technology Development	Y.J. Mii (Note 2)													
Vice President Operations/Affiliate Fabs	M.C. Tzeng													
Vice President and Chief Technology Officer Research and Development/Corporate Research	Jack Sun													
Vice President Quality and Reliability	N.S. Tsai													
Vice President Operations/Mainstream Fabs and Manufacturing Technology	J.K. Lin													
Vice President Operations/300mm Fabs	J.K. Wang	65,452	79,631	2,025	2,400	475,796	558,934	433,178	-	433,178	-	0.293%	0.322%	122
Vice President Corporate Planning Organization	Irene Sun													
Vice President Research and Development/Design and Technology Platform	Cliff Hou													
Vice President Business Development	Been-Jon Woo													
Vice President and General Counsel Legal	Sylvia Fang													
Vice President Human Resources	Connie Ma													
Vice President Research and Development/Technology Development	Y.L. Wang													
Vice President Research and Development/Integrated Interconnect & Packaging	Douglas Yu (Note 3)													
Vice President Research and Development/More-than-Moore Technologies	Alexander Kalnitsky (Note 3)													
Vice President Research and Development/Design and Technology Platform	Kevin Zhang (Note 3)													
Total		86,910	101,089	2,691	3,066	732,775	815,913	683,672	-	683,672	-	0.451%	0.480%	122

Note 1: Compensation policy, standards/packages, procedures, the linkage to operating performance and future risk exposure: The total compensation paid to Chief Executive Officer, Chief Financial Officer and General Counsel is proposed by Chairman based on their job responsibility, contribution, company performance and projected future risks the Company will face. The total compensation paid to other executive officers is proposed by Chairman and Chief Executive Officer. The proposals are reviewed by the Compensation Committee before submitted to the Board of Directors for final approval.

Note 2: Mr. Y.P. Chin and Dr. Y.J. Mii were promoted to Senior Vice President, effective November 8, 2016.

Note 3: Dr. Douglas Yu, Dr. Alexander Kalnitsky and Dr. Kevin Zhang were promoted to Vice President, effective November 8, 2016.

Note 4: Pensions funded/paid according to applicable law.

Note 5: The above-mentioned figures include the expense for the employees' cash bonuses distributed in May, August, November 2016 and February 2017, Company cars and gasoline reimbursement, but does not include compensation paid to Company drivers (totaled NT\$3,432 thousand).

Note 6: Total compensation of TSMC and all consolidated entities paid to TSMC's Chief Executive Officer and Executive Officers in 2015 were NT\$1,406,547 thousand and NT\$1,491,529 thousand respectively, accounting for 0.46% and 0.49% of 2015 net income respectively.

Compensation Paid to President & Co-CEO and Vice Presidents

	2016	
	From TSMC	From All Consolidated Entities and Non-consolidated Affiliates
NT\$0 ~ NT\$2,000,000	Rick Cassidy	None
NT\$2,000,000 ~ NT\$4,999,999	None	None
NT\$5,000,000 ~ NT\$9,999,999	Douglas Yu, Alexander Kalnitsky	Douglas Yu, Alexander Kalnitsky
NT\$10,000,000 ~ NT\$14,999,999	None	None
NT\$15,000,000 ~ NT\$29,999,999	Kevin Zhang	Kevin Zhang
NT\$30,000,000 ~ NT\$49,999,999	J.K. Wang, Irene Sun, Been-Jon Woo, Sylvia Fang, Connie Ma, Y. L. Wang	J.K. Wang, Irene Sun, Been-Jon Woo, Sylvia Fang, Connie Ma, Y. L. Wang
NT\$50,000,000 ~ NT\$99,999,999	Y.P. Chin, Y.J. Mii, M.C. Tzeng, Jack Sun, N.S. Tsai, J.K. Lin, Cliff Hou	Rick Cassidy, Y.P. Chin, Y.J. Mii, M.C. Tzeng, Jack Sun, N.S. Tsai, J.K. Lin, Cliff Hou
Over NT\$100,000,000	Mark Liu, C.C. Wei, Lora Ho, Stephen T. Tso, Wei-Jen Lo	Mark Liu, C.C. Wei, Lora Ho, Stephen T. Tso, Wei-Jen Lo
Total	22	22

2.5.3 Employees' Profit Sharing Bonus Paid to Management Team

Unit: NT\$ thousands

Title	Name	Stock (Fair Market Value)	Cash	Total Employees' Profit Sharing Bonus	Total Employees' Profit Sharing Bonus Paid to Management Team as a % of 2016 Net Income
President and Co-Chief Executive Officer	Mark Liu	-	101,588	101,588	0.030%
President and Co-Chief Executive Officer	C.C. Wei	-	101,588	101,588	0.030%
Senior Vice President, Chief Financial Officer and Spokesperson Finance	Lora Ho	-	47,318	47,318	0.014%
Senior Vice President and Chief Information Officer Information Technology, Materials Management and Risk Management	Stephen T. Tso				
Senior Vice President Research and Development/Technology Development	Wei-Jen Lo				
Senior Vice President of TSMC and President of TSMC North America	Rick Cassidy				
Senior Vice President Operations/Product Development	Y.P. Chin (Note 1)				
Senior Vice President Research and Development/Technology Development	Y.J. Mii (Note 1)				
Vice President Operations/Affiliate Fabs	M.C. Tzeng				
Vice President and Chief Technology Officer Research and Development/Corporate Research	Jack Sun				
Vice President Quality and Reliability	N.S. Tsai				
Vice President Operations/Mainstream Fabs and Manufacturing Technology	J.K. Lin				
Vice President Operations/300mm Fabs	J.K. Wang	-	433,178	433,178	0.130%
Vice President Corporate Planning Organization	Irene Sun				
Vice President Research and Development/Design and Technology Platform	Cliff Hou				
Vice President Business Development	Been-Jon Woo				
Vice President and General Counsel Legal	Sylvia Fang				
Vice President Human Resources	Connie Ma				
Vice President Research and Development/Technology Development	Y. L. Wang				
Vice President Research and Development/Integrated Interconnect & Packaging	Douglas Yu (Note 2)				
Vice President Research and Development/More-than-Moore Technologies	Alexander Kalnitsky (Note 2)				
Vice President Research and Development/Design and Technology Platform	Kevin Zhang (Note 2)				
Total		-	683,672	683,672	0.204%

Note 1: Mr. Y.P. Chin and Dr. Y.J. Mii were promoted to Senior Vice President, effective November 8, 2016.

Note 2: Dr. Douglas Yu, Dr. Alexander Kalnitsky and Dr. Kevin Zhang were promoted to Vice President, effective November 8, 2016.